

07-18-2006

DOCKET: CU-4858 WWP

799416270

Form PTO-1595 (Rev. 06/04)  
OMB No. 0651-0027 (exp. 6/30/2005)U.S. DEPARTMENT OF COMMERCE  
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**PATENTS ONLY**

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)/Execution Date(s):**

- 1) JUNG, Young Hy  
2) LEE, Chan Sun

Execution Date(s) June 26, 2006Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No**3. Nature of conveyance:**

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other \_\_\_\_\_

**2. Name and address of receiving party(ies)**Name: HYNIX SEMICONDUCTOR INC.

Internal Address: \_\_\_\_\_

Street Address: San 136-1, Ami-ri,  
Bubal-eub, Icheon-si, Kyoungki-do,  
Republic of Korea  
City: \_\_\_\_\_

State: \_\_\_\_\_

Country: \_\_\_\_\_ Zip: \_\_\_\_\_

Additional name(s) & address(es) attached? ☐ Yes ☒ No**4. Application or patent number(s):**☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

07/14/2006 HDEMESS1 00000017 11485119

(40.00 DP)

Additional numbers attached? ☐ Yes ☒ No**5. Name and address to whom correspondence concerning document should be mailed:**Name: Richard J. Streit

Internal Address: \_\_\_\_\_

Street Address: c/o Ladas & Parry  
224 South Michigan Avenue

City: ChicagoState: Illinois Zip: 60604Phone Number: (312) 427-1300

Fax Number: \_\_\_\_\_

Email Address: \_\_\_\_\_

**6. Total number of applications and patents involved:**1**7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00**

- ☐ Authorized to be charged by credit card  
☐ Authorized to be charged to deposit account  
☒ Enclosed  
☐ None required (government interest not affecting title)

**8. Payment Information**

a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_

b. Deposit Account Number 12-0400Authorized User Name Ladas & Parry LLP**9. Signature:**Woochoon W. Park

Signature

July 12, 2006

Date

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 3

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**PATENT**  
**REEL: 018057 FRAME: 0251**

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**UNITED STATES OF AMERICA**  
**ASSIGNMENT**

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In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

**ASSIGNOR:**

Name : Young Hy JUNG

Address : 908-2006, Halla Vivaldi, Gangnam-maeul, Sangha-ri, Guseong-eub, Yongin-si, Kyoungki-do, Korea

Name : Chan Sun LEE

Address : 1-102, Woosung Apt., 19 Cheonho-dong, Gangdong-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

**ASSIGNEE:**

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

SEMICONDUCTOR PACKAGE STACK WITH THROUGH-VIA CONNECTION

(TITLE)

and which is found in *(check one applicable item below)*

☒ U.S. patent application executed on even date herewith

☐ U.S. Application Serial No. \_\_\_\_\_ filed on \_\_\_\_\_

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters

**PATENT**

**RECORDED: 07/12/2006**

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